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11/15/02
Atty. Docket No. 8037-1001 *Muller*

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Kimio TSUNEMASU

Confirmation No. 5276

Serial No. 10/073,196

GROUP 2827

Filed February 13, 2002

Examiner J. Mitchell

SEMICONDUCTOR DEVICE CAPABLE OF
PREVENTING SOLDER BALLS FROM BEING
REMOVED IN REINFORCING PAD

AMENDMENT

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of August 12, 2002,
please amend the above-identified application as follows:

IN THE ABSTRACT:

Rewrite the Abstract of the Disclosure as on the
accompanying separate sheet.

IN THE SPECIFICATION:

Page 8, replace the paragraph beginning on line 9 as
follows:

A1
--In the present invention, the semiconductor device
according to the preferred embodiment is mounted on a principle
surface (a surface on which the semiconductor device is mounted)
of a substrate, such as a printed wiring substrate, and the like
to be connected with a circuit formed on the principle surface.
The semiconductor device comprises a body portion having a